



QLSP1608R-293 V1.0
(0805 Red LED)



Product Outline:

This is the much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.

Features:

- Compatible with automatic placement equipment.
- RoHS compliant
- Compatible with infrared and vapor phase reflow solder process.
- Custom Bin available upon special request
- View angle typ. 130°
- 0.8mm Height

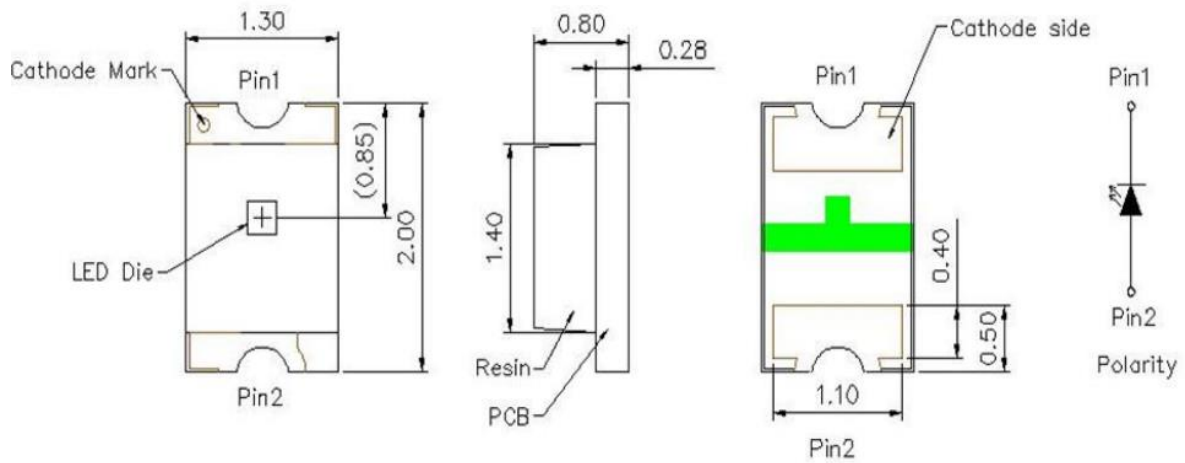
Application:

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

Compliance and Certification:

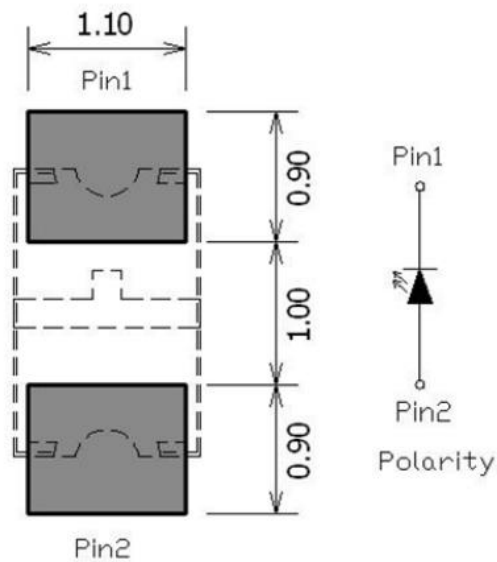


Mechanical Property: (Dimension)



- * All dimensions are in millimeters,
- * Tolerances are $\pm 0.10\text{mm}$.

Recommended Solder footprint:



- * All dimensions are in millimeters.
- * Reflow soldering must not be performed more than twice.



Characteristics

■ Absolute Maximum Ratings

(Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
DC Forward Current	I_f	20	mA
Pulse Forward Current (Duty 1/10 @1KHz)	I_{FP}	100	mA
Total Power Dissipation	P_d	48	mW
Electrostatic Discharge (HBM)	ESD	2000	V
Storage Temperature	T_{ST}	-40 ~ +100	°C
Operation Temperature	T_{OP}	-40 ~ +85	°C
Soldering Temperature	T_{SOL}	260 < 10 sec	°C

(1) Proper current rating must be observed to maintain junction temperature below maximum at all time

■ Electrical / Optical Characteristic

(Ta=25 oC)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I_v	71.5	112.5	180	mcd	$I_f=20mA$
Peak Wavelength	λ_p	615	620	630	nm	
Dominant Wavelength	λ_d		624		nm	
Forward Voltage	V_f	2.0		2.4	V	
View Angle	θ		130		deg	

- (1). Tolerance of Luminous Intensity: $\pm 11\%$
- (2). Tolerance of Dominant Wavelength $\pm 1nm$
- (3). Tolerance of measurement: $V_F = \pm 0.1V$



■ Groups

Forward Voltage (V_F) Bin:

VF Rank (V)				Condition
Color	Code name	Low	High	unit
RED	E18	1.6	2.4	IF=20mA

Luminous Intensity Bin:

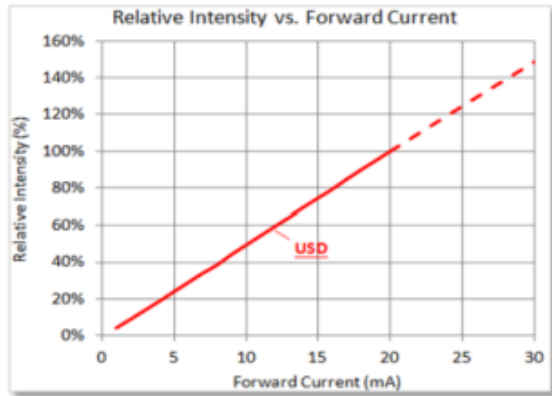
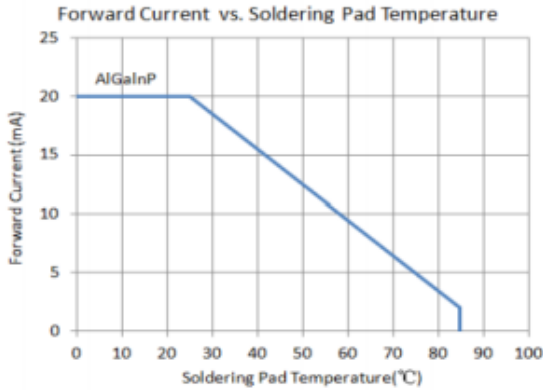
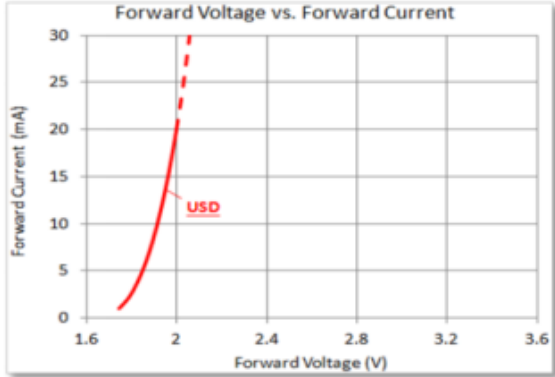
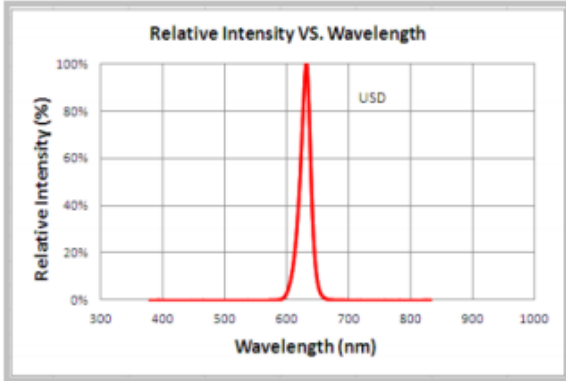
Rank (mcd)				Condition
Color	Code name	Low	High	Unit
RED	Q	71.50	112.5	IF=20mA
	R	112.5	180.0	

Dominant Wavelength Bin:

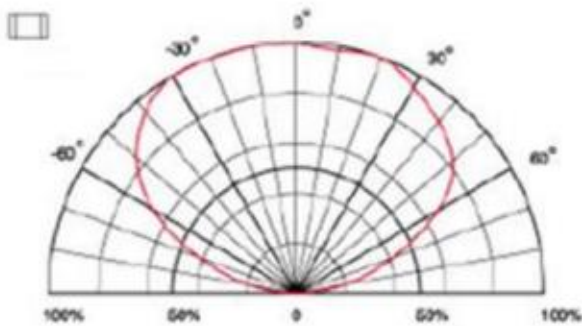
Rank (nm)				Condition
Color	Code name	Low	High	Unit
RED	AC	615	630	IF=20mA



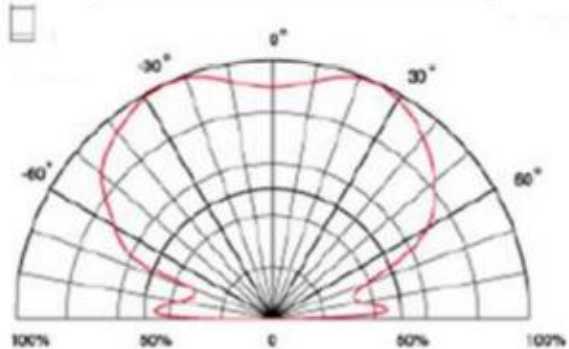
Characteristic Curves



Directive Characteristics



Directive Characteristics



■ Reliability test:

No	Item	Condition	Time/Cycle	Sample size
1	Steady State Operating Life of Room Temperature	25°C Operating	1000 Hrs	20 pcs
2	Steady State Operating Life of Low Temperature -40°C	-40°C Operating	1000 Hrs	20 pcs
3	Steady State Operating Life of Low Temperature 60°C	60°C Operating	1000 Hrs	20 pcs
4	Steady State Operating Life of Low Temperature 85°C	85°C Operating	1000 Hrs	20 pcs
5	Low temperature storage -40°C	-40°C Storage	1000 Hrs	20 pcs
6	High temperature storage 100°C	100°C Storage	1000 Hrs	20 pcs
7	Steady State Operating Life of High Humidity Heat 60°C 90%	60°C/90% Operating	1000 Hrs	20 pcs
8	Steady State Pulse Operating Life Condition	25°C 10Hz duty=1/10 Operating	200 Cycle	20 pcs
9	Resistance to soldering heat on PCB (JEDEC MSL3)	pre-store@60°C, 60%RH for 52hrs Tsltd max.=260 10sec	3 Times	20 pcs
10	Heat Cycle Test (JEDEC MRC)	25°C~65°C~-10°C, 90%RH, 24hr/1cycle	10 Cycle	20 pcs
11	Thermal shock	-40°C/ 20min~ 5min~100°C /20min	300 Cycle	20 pcs

■ Judgment Criteria:

Item	Symbol	Test Condition	Judgment Criteria
Forward Voltage	Vf	R : IF=20 mA	$\Delta Vf < 10\%$
Luminous Flux	Iv		$\Delta Iv < 30\%$

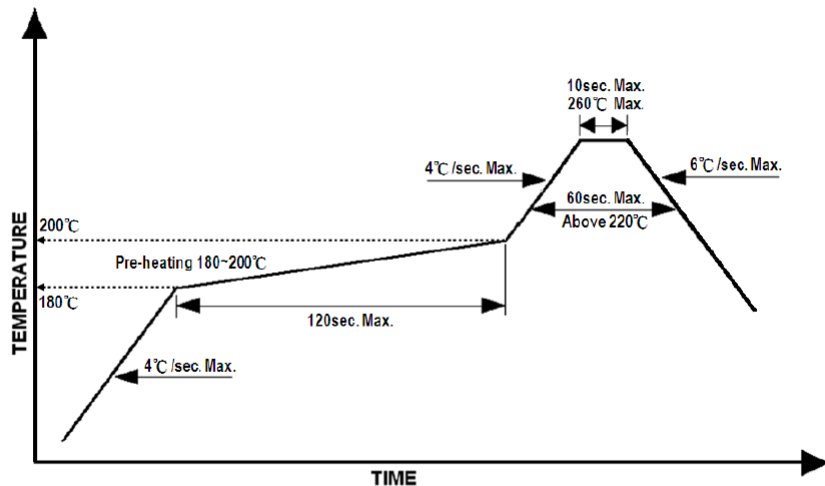


Solder Profile:

-The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

1. Operating temp.: Above 217 °C ,60~150 sec.
2. Peak temp.:260 °C Max.,10sec Max.
3. Reflow soldering should not be done more than two times.
4. Never attempt next process until the component is cooled down to room temperature after reflow.
5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

Lead-free Solder Profile



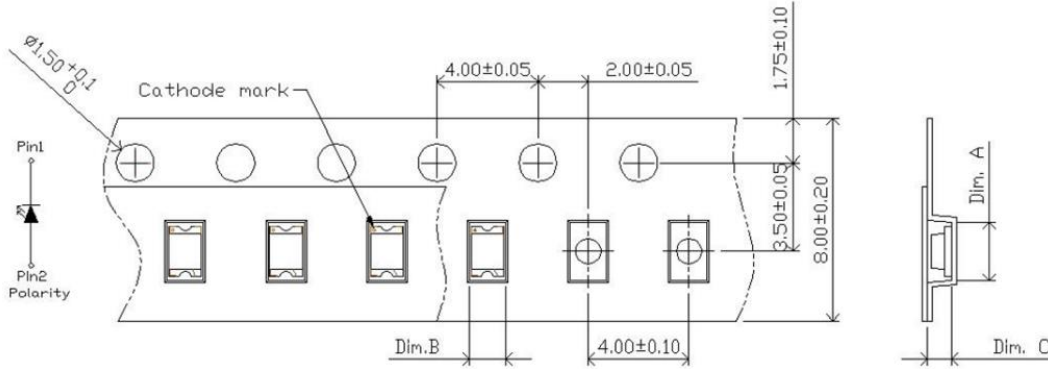
Reworking

- Rework should be completed within 5 seconds under 260°C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.



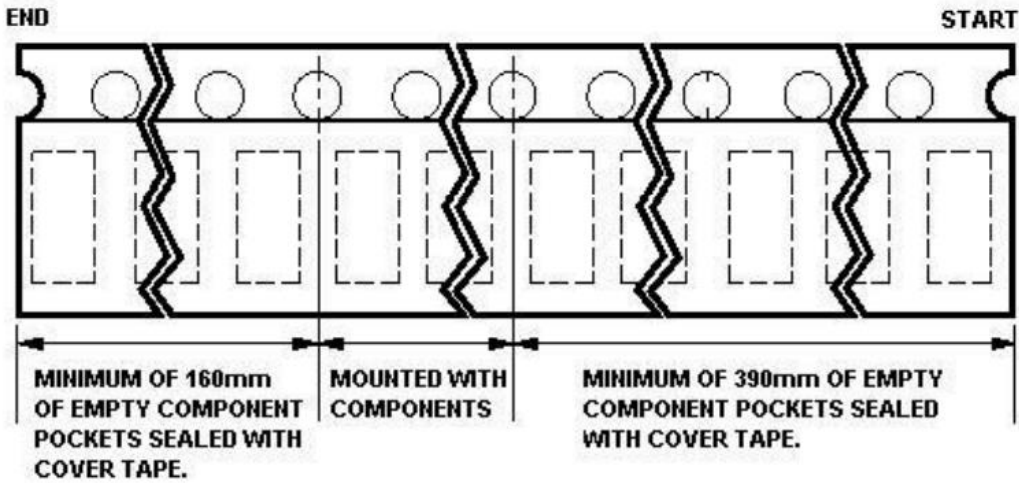
Taping & Packing:

Tape Dimension



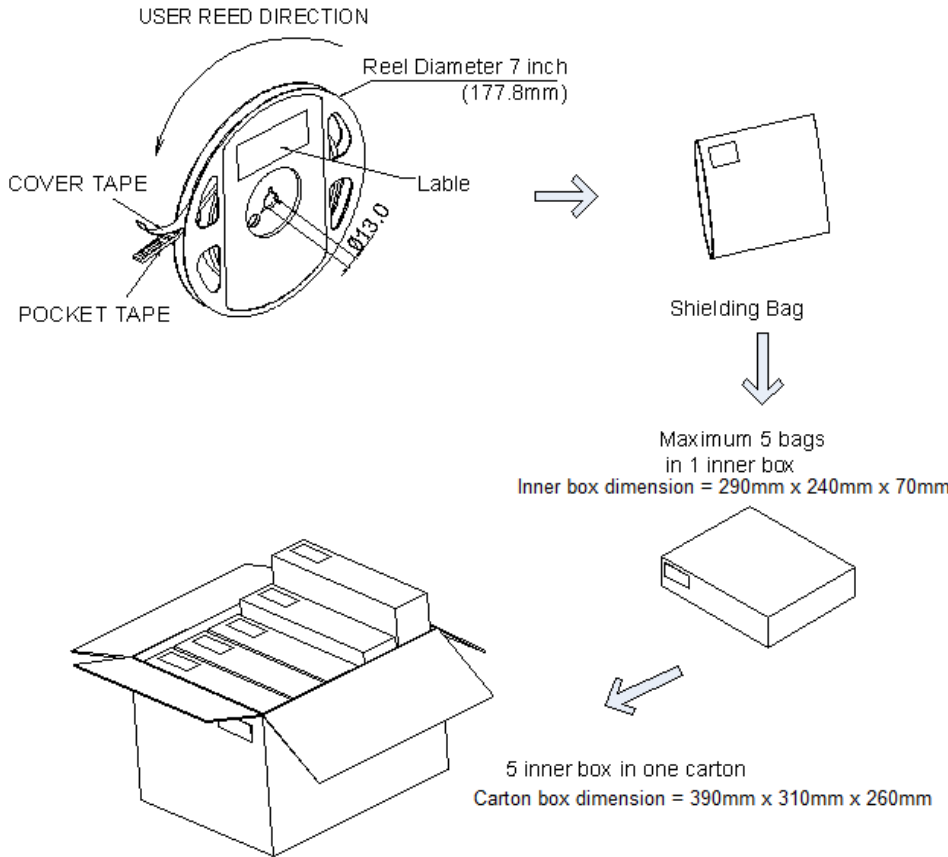
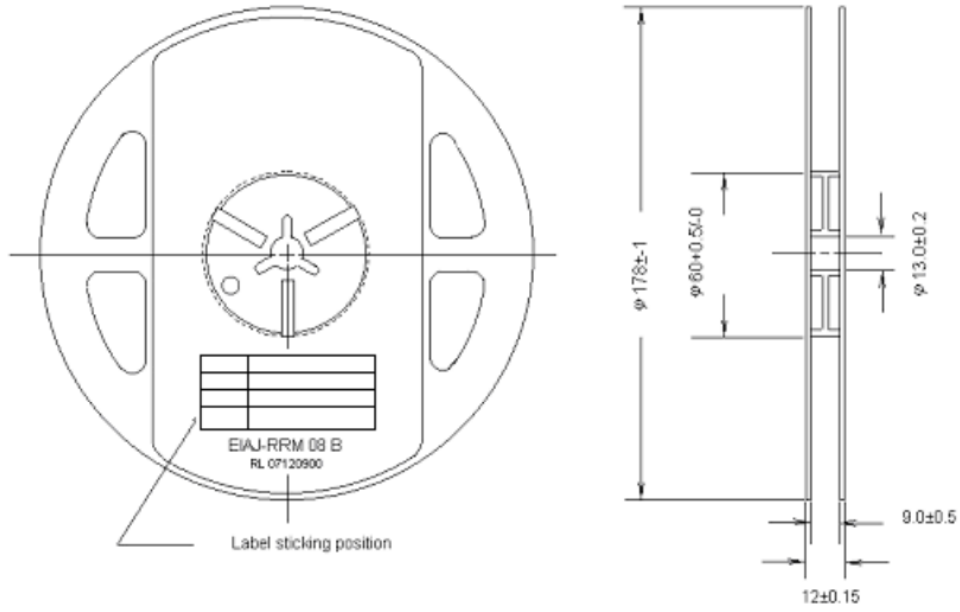
Dim. A	Dim. B	Dim. C	Q'ty/Reel
2.20±0.05	1.42±0.05	0.88±0.05	4K

Unit : mm

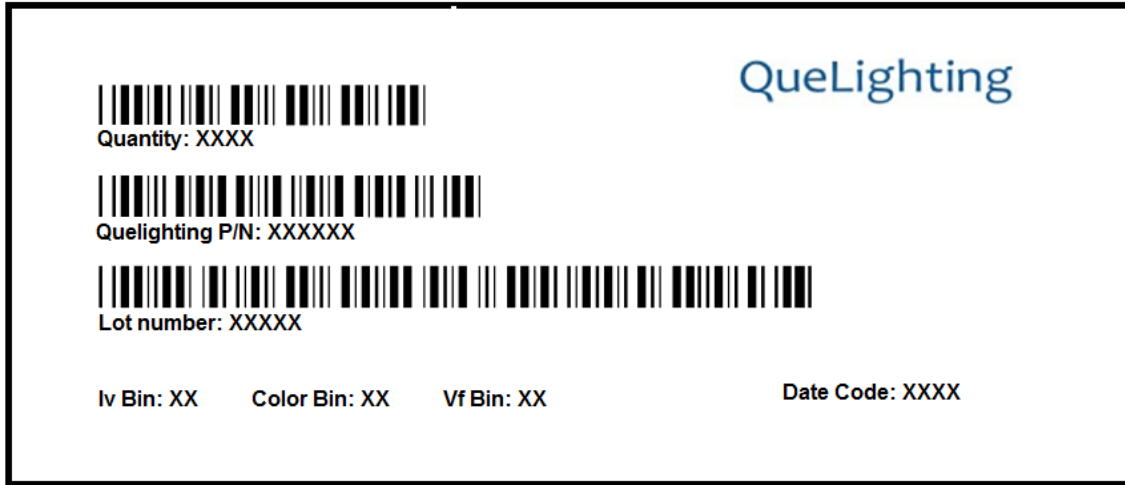


Packing

Reel Dimension



Labeling



Ordering Information:

Part #	Multiple Quantities	Quantity per Reel
QLSP1608R-293		3000 pcs

Revision History:

Revision Date:	Changes:	Version #:
03-13-2021	Initial release	1.0

